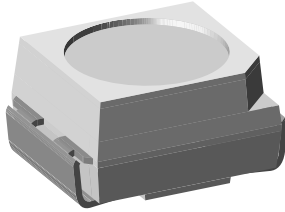


High Speed Infrared Emitting Diode, 850 nm, Surface Emitter Technology



LINKS TO ADDITIONAL RESOURCES



DESCRIPTION

The VSMY385011X02 is an infrared, 850 nm emitting diode based on surface emitter technology with high radiant intensity, high optical power and high speed, molded in a PLCC-2 package for surface mounting (SMD).

v

FEATURES

- Package type: surface-mount
- Package form: PLCC-2
- Dimensions (L x W x H in mm): 3.5 x 2.8 x 1.75
- AEC-Q102 qualified
- Peak wavelength: $\lambda_p = 850 \text{ nm}$
- Angle of half intensity: $\phi = \pm 60^\circ$
- Floor life: 168 h, MSL 3, according to J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization:
for definitions of compliance please see www.vishay.com/doc?99912



RELEASED FOR APPLICATIONS

- Infrared radiation source for operation with CMOS cameras (illumination)
- High speed IR data transmission
- Automotive sensors
- Light curtain

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY385011X02-GS08	Tape and reel	MOQ: 7500 pcs, 1500 pcs/reel	PLCC-2
VSMY385011X02-GS18	Tape and reel	MOQ: 8000 pcs, 8000 pcs/reel	PLCC-2

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	5	V
Forward current ⁽¹⁾		I_F	100	mA
Surge forward current	$t_p = 100 \mu\text{s}$	I_{FSM}	500	mA
Power dissipation		P_V	180	mW
Junction temperature		T_j	110	$^\circ\text{C}$
Operating temperature range		T_{amb}	-40 to +105	$^\circ\text{C}$
Storage temperature range		T_{stg}	-40 to +110	$^\circ\text{C}$
Soldering temperature	According to Fig. 7, J-STD-020	T_{sd}	260	$^\circ\text{C}$
Thermal resistance junction to ambient	J-STD-051, soldered on PCB	R_{thJA}	240	K/W

Note

- ⁽¹⁾ Minimum forward current $I_{F \text{ min.}} = 5 \text{ mA}$

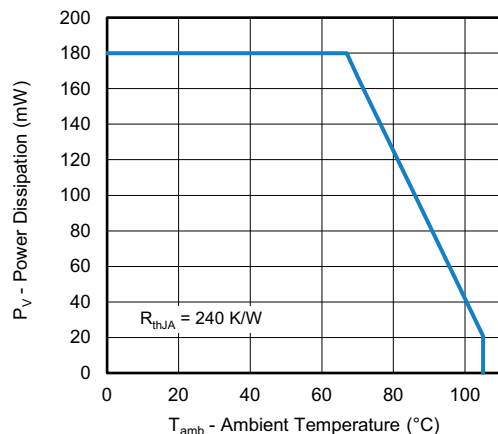


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

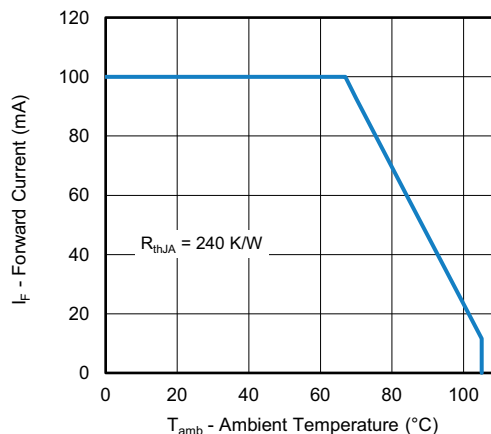


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	V_F	-	1.6	1.9	V
	$I_F = 0.5\text{ A}$, $t_p = 100\text{ }\mu\text{s}$	V_F	-	2.1	-	V
Temperature coefficient of V_F	$I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	TK_{VF}	-	-1.5	-	mV/K
Reverse current		I_R	Not designed for reverse operation			μA
Junction capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$, $E = 0$	C_j	-	15	-	pF
Radiant power	$I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	ϕ_e	-	35	-	mW
Temperature coefficient of ϕ_e	$I_F = 100\text{ mA}$	$TK\phi_e$	-	-0.4	-	%/K
Angle of half intensity		ϕ	-	± 60	-	$^{\circ}$
Peak wavelength	$I_F = 100\text{ mA}$	λ_p	-	850	-	nm
Spectral bandwidth	$I_F = 100\text{ mA}$	$\Delta\lambda$	-	27	-	nm
Temperature coefficient of λ_p	$I_F = 100\text{ mA}$	$TK\lambda_p$	-	0.3	-	nm/K
Rise time	$I_F = 30\text{ mA}$	t_r	-	25	-	ns
Fall time	$I_F = 30\text{ mA}$	t_f	-	25	-	ns

TYPE DEDICATED CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	BINNED GROUP	SYMBOL	MIN.	MAX.	UNIT
Radiant intensity	$I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	A	I_e	9.4	11.1	mW/sr
		B		10.9	12.6	
		C		12.4	14.1	

Note

- Each 1500 reel will contain a single group. The label on the bag will indicate which binned group is the bag. A specific group cannot be ordered. Production shipment containing multiple bags will likely include multiple groups. Please design accordingly

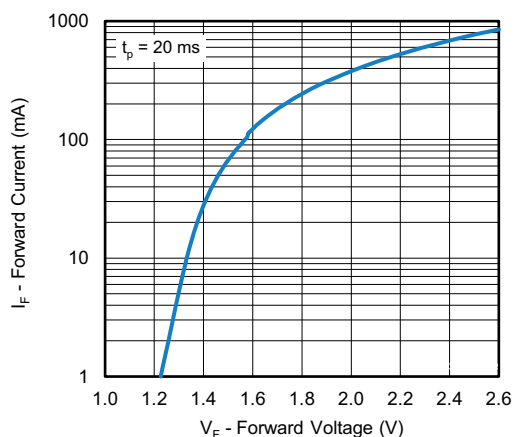
BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 3 - Forward Current vs. Forward Voltage

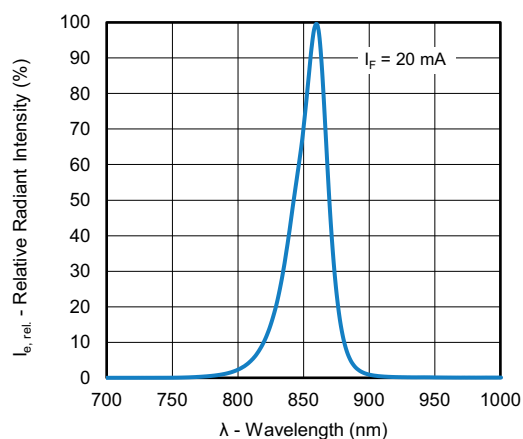


Fig. 5 - Relative Radiant Power vs. Wavelength

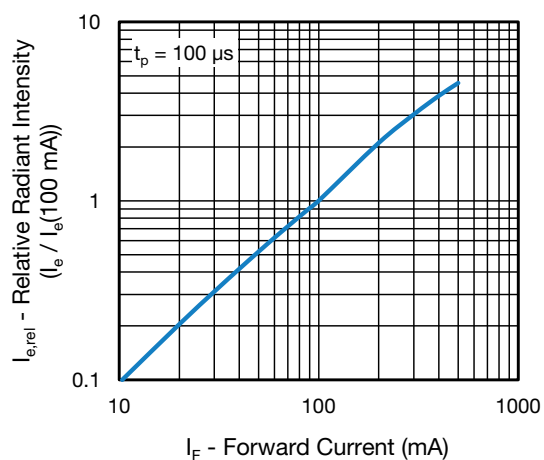


Fig. 4 - Radiant Intensity vs. Forward Current

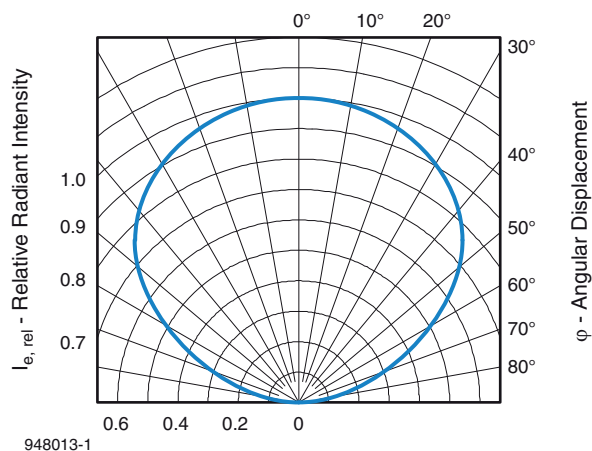
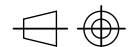
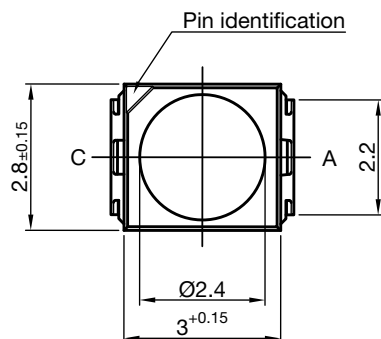
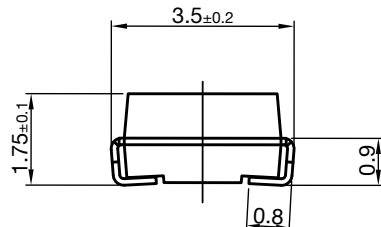


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

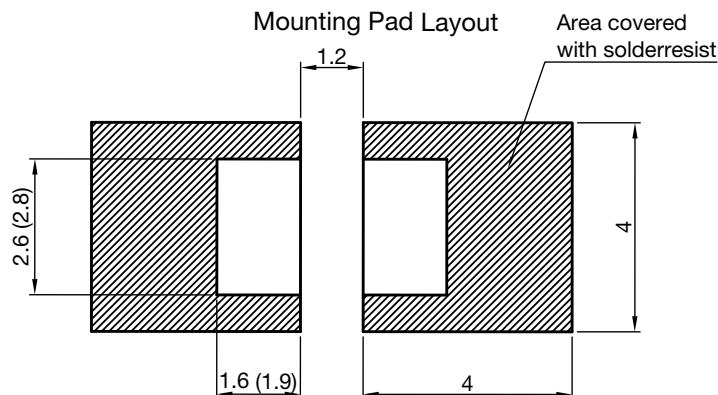
PACKAGE DIMENSIONS in millimeters


Technical drawings
according to DIN
specifications

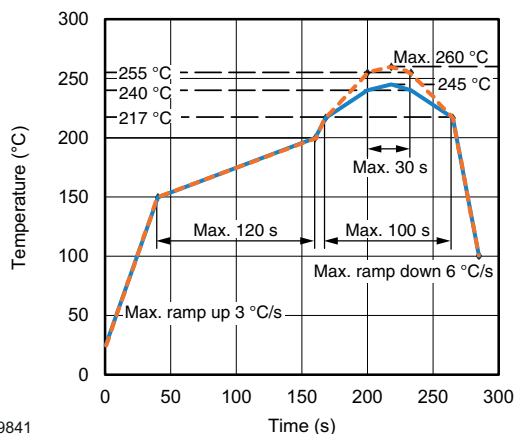
Dimensions in mm

Drawing-No.: 6.541-5067.02-4

Issue: 5; 23.09.13



Dimensions: Reflow and vapor phase (wave soldering)

SOLDER PROFILE


19841

Fig. 7 - Lead (Pb)-free Reflow Solder Profile
According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

Conditions: $T_{amb} < 30\text{ °C}$, $RH < 60\%$

Moisture sensitivity level 3, according to J-STD-033D

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), $RH < 5\%$.

TAPE AND REEL

PLCC-2 components are packed in antistatic blister tape (DIN IEC (CO) 564) for automatic component insertion. Cavities of blister tape are covered with adhesive tape.

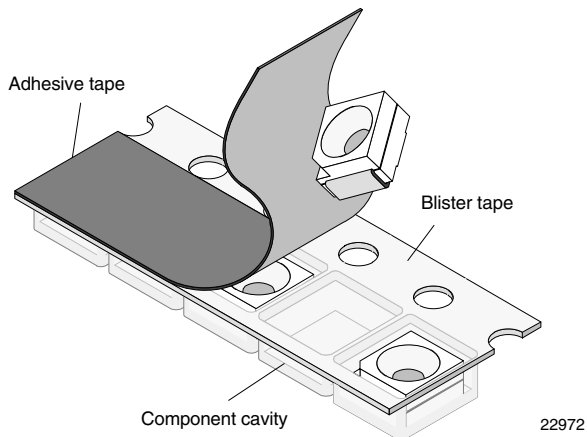


Fig. 8 - Blister Tape

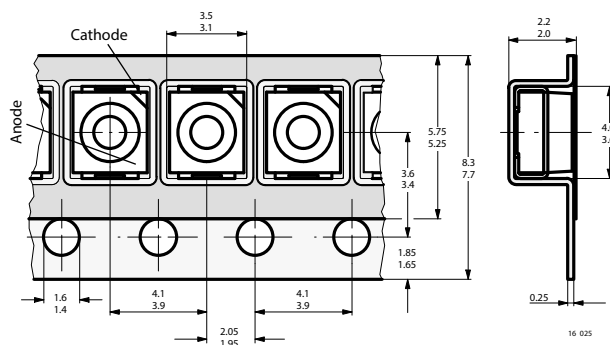


Fig. 9 - Tape Dimensions in mm for PLCC-2

MISSING DEVICES

A maximum of 0.5 % of the total number of components per reel may be missing, exclusively missing components at the beginning and at the end of the reel. A maximum of three consecutive components may be missing, provided this gap is followed by six consecutive components.

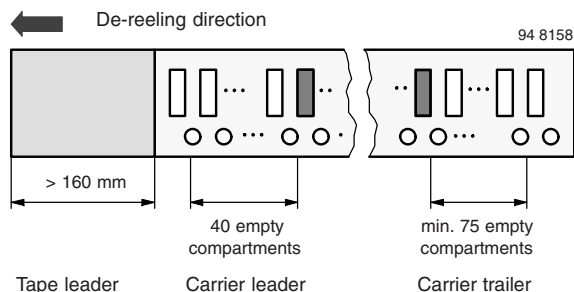


Fig. 10 - Beginning and End of Reel

The tape leader is at least 160 mm and is followed by a carrier tape leader with at least 40 empty compartments. The tape leader may include the carrier tape as long as the cover tape is not connected to the carrier tape. The least component is followed by a carrier tape trailer with a least 75 empty compartments and sealed with cover tape.

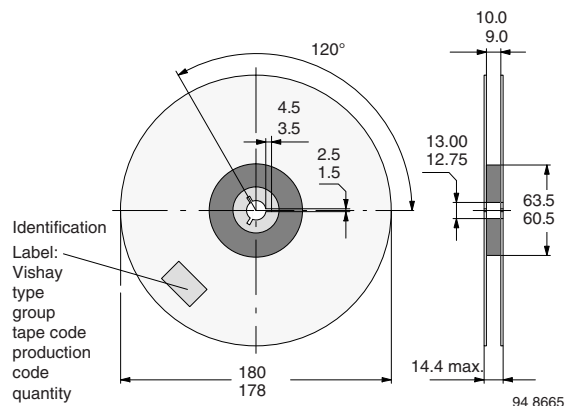


Fig. 11 - Dimensions of Reel-GS08

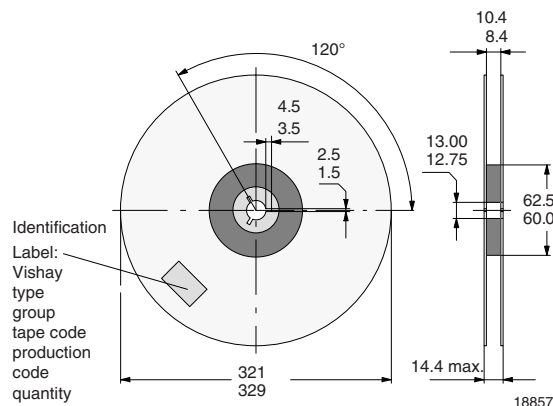


Fig. 12 - Dimensions of Reel-GS18

COVER TAPE REMOVAL FORCE

The removal force lies between 0.1 N and 1.0 N at a removal speed of 5 mm/s. In order to prevent components from popping out of the blisters, the cover tape must be pulled off at an angle of 180° with regard to the feed direction.



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